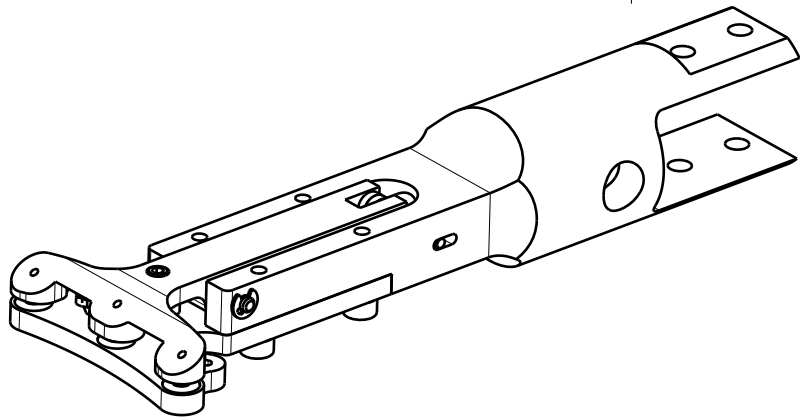
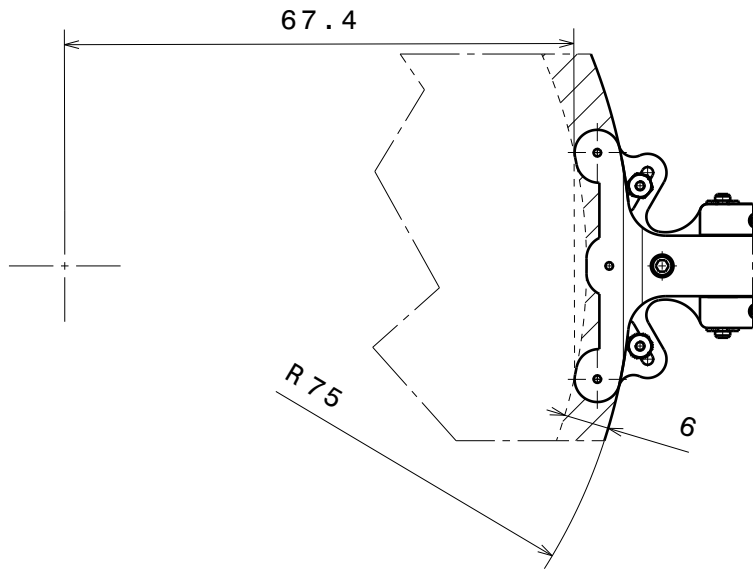


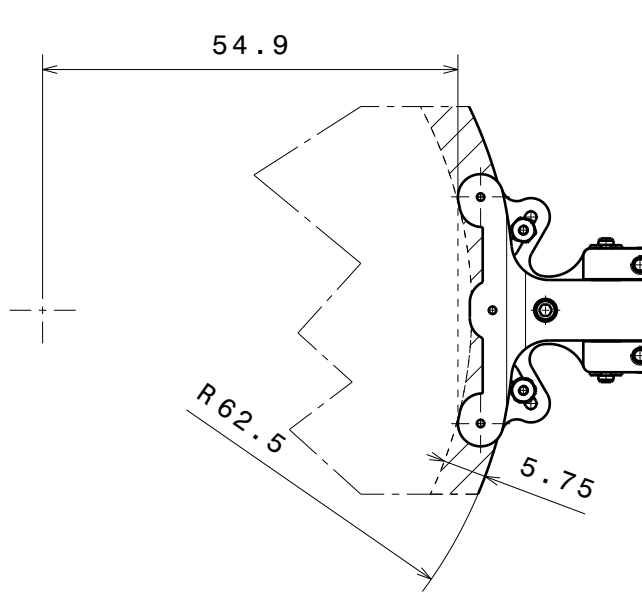


Material: fully UHV compatible		nominal dimensions >30mm		DIN ISO 2768-f-H DIN ISO 2768-m-K excluding Sym./Runout	
Straight Pincer High Force Version for Wafer PGHFWMWAF		Sym./Runout >30mm		DIN ISO 2768-H	
		formed part dimensions		DIN ISO 2768-f-H	
		Scale		Drawn C.Weiss	
		Date		03.05.2018	
Ferrovac GmbH CH-8050 Zurich		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF FERROVAC GMBH. ANY REPRODUCTION IN PART OR AS WHOLE WITHOUT OUR PERMISSION IS PROHIBITED.		1 : 1	
				Changed	
				PGHFWMWAF	
		Rev. A		A4 sheet 1/1	

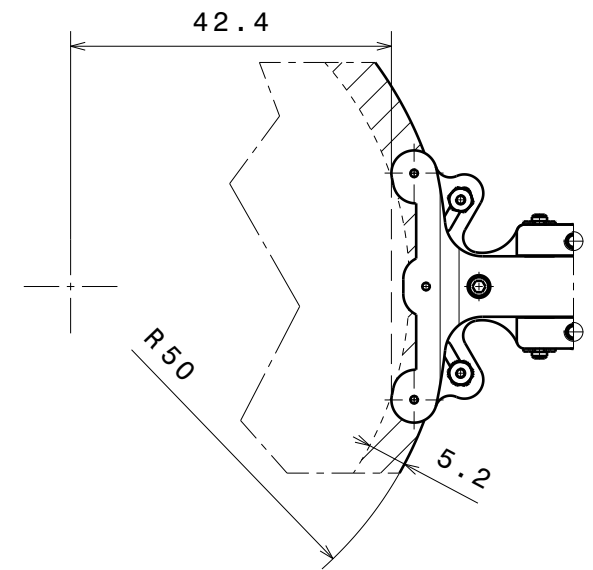
"6 inch Wafer



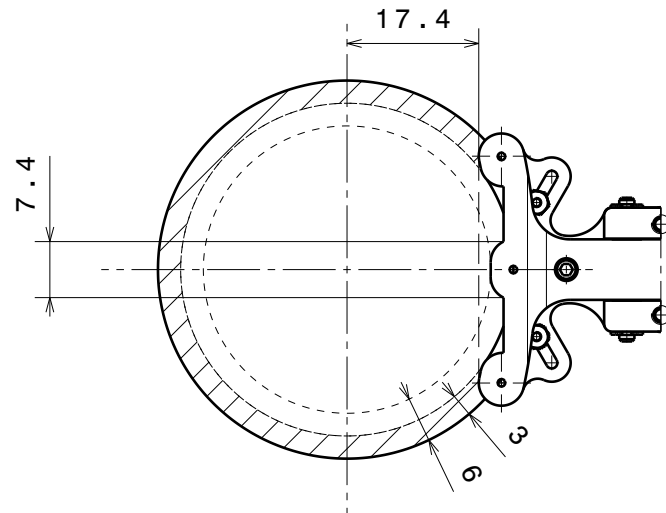
"4.9 inch Wafer



"4 inch Wafer



"2 inch Wafer



Ra 0.8 (✓) $\begin{matrix} +0.2 \\ +0.1 \end{matrix}$ $\begin{matrix} -0.1 \\ -0.2 \end{matrix}$

Material: fully UHV compatible

Straight Pincer High Force
Version for Wafer

PGHFWMWAF

Ferrovac GmbH
CH-8050 Zurich

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nominal	≤30mm	DIN ISO 2768-f-H
dimensions	>30mm	DIN ISO 2768-m-K excluding Sym./Runout
Sym./Runout	>30mm	DIN ISO 2768-H
formed part dimensions		DIN ISO 2768-f-H
Scale	Drawn	C.Weiss
	Date	03.05.2018
	Changed	
		PGHFWMWAF
Rev.	A	A4 sheet 1/1

1:1